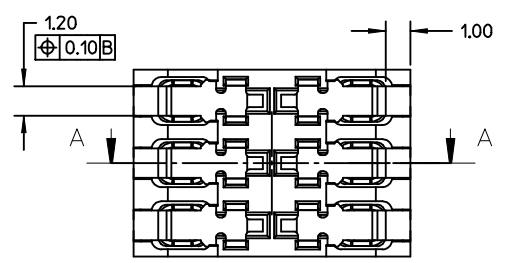
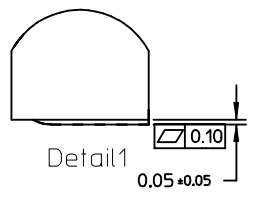
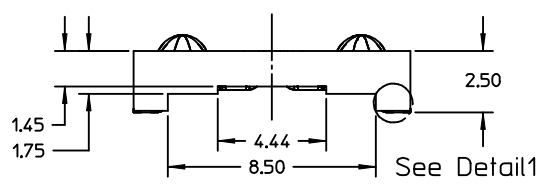
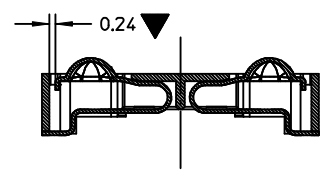
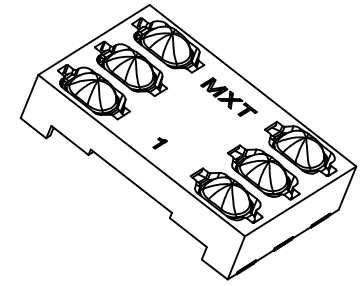
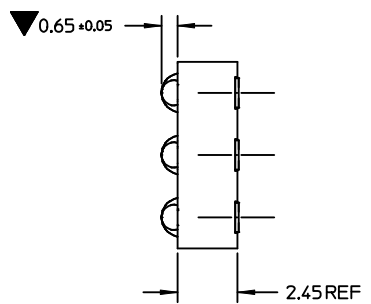
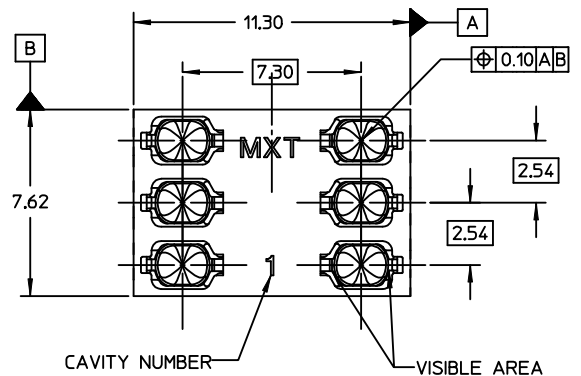


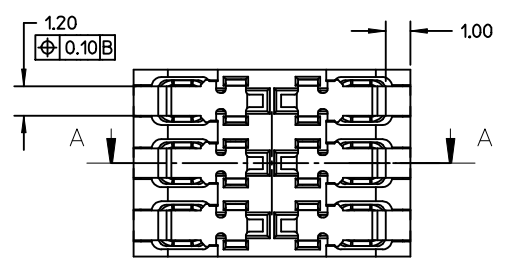
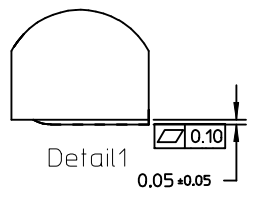
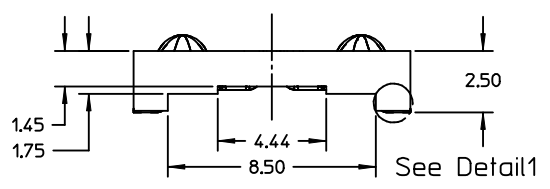
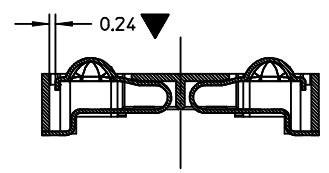
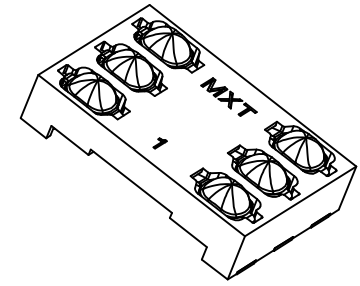
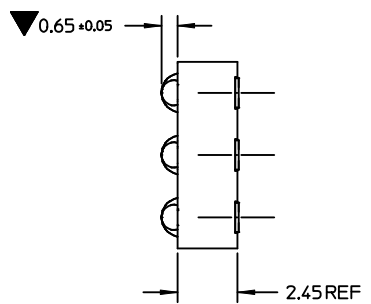
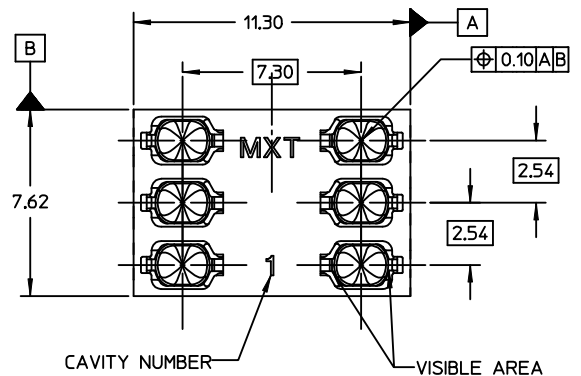
PART NAME	DRAWING NUMBER	PART NUMBER
HOUSING	E-67687-802	676872502
TERMINAL	E-67687-804	676872504



- NOTES:
- MATERIAL:
    - HOUSING: LCP, 30% GLASS FILLED, UL94V-0, BLACK
    - TERMINAL: PHOSPHOR BRONZE C5210R-H, THICKNESS : 0.15MM
  - PLATING:
    - SIM CARD CONTACT AREA PLATING: 30u" MIN GOLD OVER 50u" MIN NICKEL PLATING
    - PCB SOLDERING AREA PLATING: 120u" MIN TIN-LEAD OVER 50u" MIN NICKEL PLATING
    - VISIBLE AREA PLATING: GOLD FLASH OVER 50u" MIN NICKEL PLATING
  - PACKAGING: TAPE REEL
  - PRODUCT SPECIFICATION REFER TO PS-67687-001

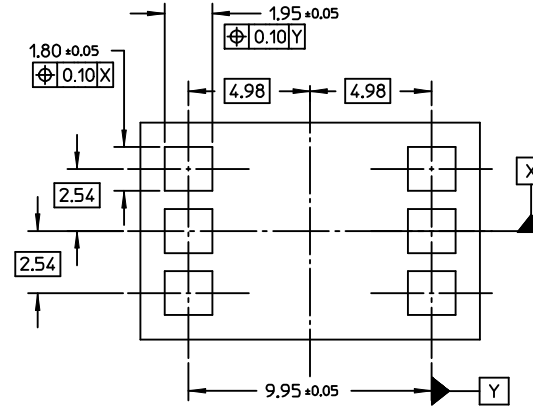
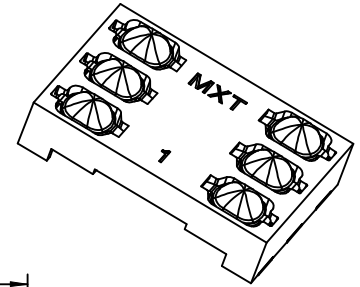
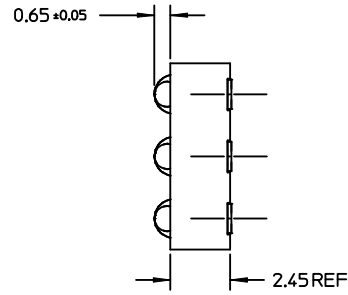
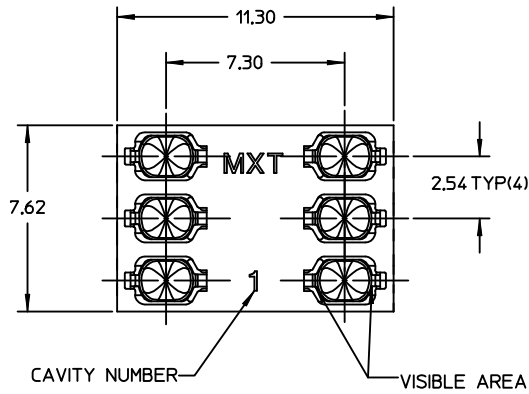
EC NO: SH2003-0071 DRWN: SSUN 2003/07/01 CHKD: 2003/07/04 APPR: SHUANG 2003/07/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY	
	DESCRIPTION -2 -0	mm	INCH	DIMENSION STYLE MM ONLY		TITLE ASSEMBLY OF SIM CARD CONNECTOR	
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY SSUN	DATE 2003/06/16	MOLEX INCORPORATED MATERIAL NO. 676872501 DOCUMENT NO. E-67687-803 SHEET NO. 1 OF 1	
		2 PLACES ± 0.05 ± ---	1 PLACE ± 0.10 ± ---	CHECKED BY	DATE		
ANGULAR ± 2 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

PART NAME	DRAWING NUMBER	PART NUMBER
HOUSING	E-67687-802	676872502
TERMINAL	E-67687-804	676872504

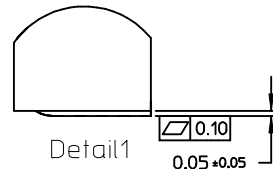
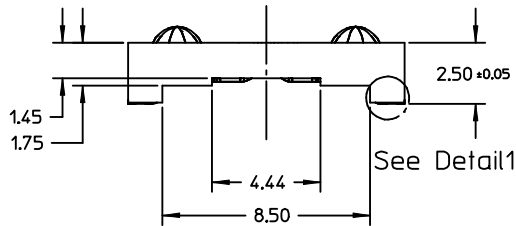


- NOTES:
- 1 MATERIAL:  
HOUSING: LCP, 30% GLASS FILLED, UL94V-0, BLACK  
TERMINAL: PHOSPHOR BRONZE C5210R-H, THICKNESS : 0.15MM
  - 2. PLATING:  
SIM CARD CONTACT AREA PLATING: 30u" MIN GOLD OVER 50u" MIN NICKEL PLATING  
PCB SOLDERING AREA PLATING: 120u" MIN TIN-LEAD OVER 50u" MIN NICKEL PLATING  
VISIBLE AREA PLATING: GOLD FLASH OVER 50u" MIN NICKEL PLATING
  - 3. PACKAGING: TAPE REEL
  - 4. PRODUCT SPECIFICATION REFER TO PS-67687-001

EC NO: SH2003-0071 DRWN: SSUN 2003/07/01 CHKD: 2003/07/04 APPR: SHUANG 2003/07/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY
	DESCRIPTION -2 -0	mm	INCH	DIMENSION STYLE MM ONLY		TITLE ASSEMBLY OF SIM CARD CONNECTOR MOLEX INCORPORATED
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY SSUN	DATE 2003/06/16	
		2 PLACES ± 0.05 ± ---	1 PLACE ± 0.10 ± ---	CHECKED BY	DATE	
ANGULAR ± 2 °		APPROVED BY	DATE	MATERIAL NO. 676872501	DOCUMENT NO. E-67687-803	
REV A	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



RECOMMEND PCB LAYOUT



NOTES:

1.MATERIAL:

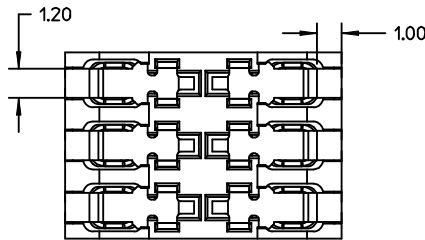
HOUSING: HIGH TEMPERATURE PLASTIC, GLASS FILLED,UL94V-0,BLACK  
 TERMINAL:COPPER ALLOY

2.PLATING:

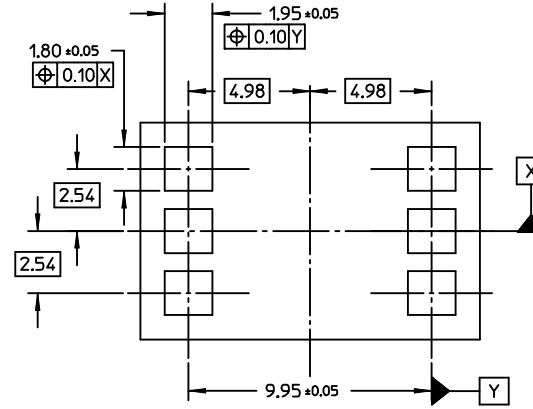
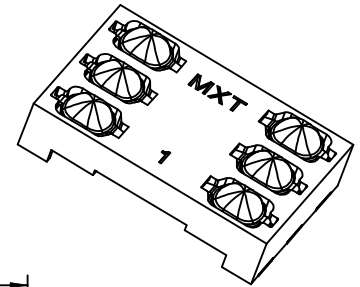
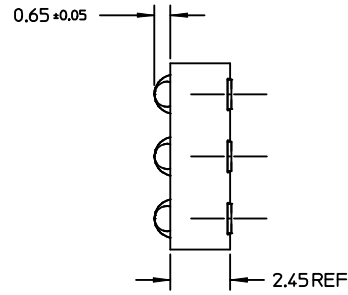
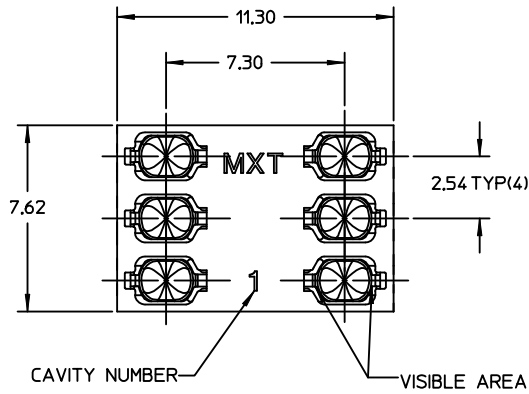
SIM CARD CONTACT AREA PLATING: 30u" MIN GOLD OVER 50u" MIN NICKEL PLATING  
 PCB SOLDERING AREA PLATING: 120u" MIN TIN-LEAD OVER 50u" MIN NICKEL PLATING  
 VISIBLE AREA PLATING: GOLD FLASH OVER 50u" MIN NICKEL PLATING

3.PACKAGING: TAPE REEL

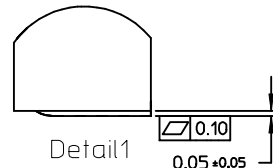
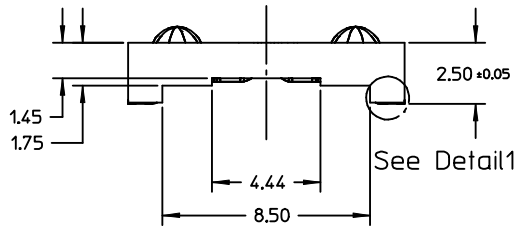
4.PRODUCT SPECIFICATION REFER TO PS-67687-001



EC NO: SH2003-0071 DRWN:SSUN 2003/07/01 CHKD: 2003/07/04 APPR:SHUANG 2003/07/04	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY	
	DESCRIPTION -0 C=0	mm	INCH	DIMENSION STYLE MM ONLY		TITLE SIM CARD CONNECTOR SALES DRAWING	
		4 PLACES ± ---	± ---	DRAWN BY SSUN	DATE 2003/06/16		
		3 PLACES ± ---	± ---	CHECKED BY	DATE		
2 PLACES ± 0.2	± ---	APPROVED BY		DATE	MOLEX INCORPORATED MATERIAL NO. 676872501 DOCUMENT NO. SD-67687-801 SHEET NO. 1 OF 1		
1 PLACE ± 0.25	± ---	DRAFT WHERE APPLICABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		MUST REMAIN WITHIN DIMENSIONS					



RECOMMEND PCB LAYOUT



NOTES:

1.MATERIAL:

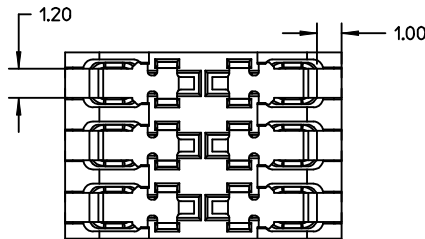
HOUSING: HIGH TEMPERATURE PLASTIC, GLASS FILLED,UL94V-0,BLACK  
 TERMINAL:COPPER ALLOY

2.PLATING:

SIM CARD CONTACT AREA PLATING: 30u" MIN GOLD OVER 50u" MIN NICKEL PLATING  
 PCB SOLDERING AREA PLATING: 120u" MIN TIN-LEAD OVER 50u" MIN NICKEL PLATING  
 VISIBLE AREA PLATING: GOLD FLASH OVER 50u" MIN NICKEL PLATING

3.PACKAGING: TAPE REEL

4.PRODUCT SPECIFICATION REFER TO PS-67687-001



EC NO: SH2003-0071 DRWN:SSUN 2003/07/01 CHKD: 2003/07/04 APPR:SHUANG 2003/07/04	QUALITY SYMBOLS ▽ = 0 ∇ = 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± 0.25 ± ---	DIMENSION STYLE MM ONLY	TITLE SIM CARD CONNECTOR SALES DRAWING			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRAWN BY SSUN	DATE 2003/06/16	MOLEX INCORPORATED	
		APPROVED BY		DATE	MATERIAL NO. 676872501	DOCUMENT NO. SD-67687-801	SHEET NO. 1 OF 1